

## SGH15N60RUF

### Short Circuit Rated IGBT

#### General Description

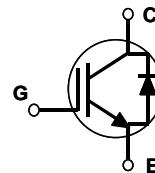
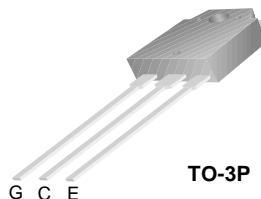
Fairchild's RUF series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUF series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

#### Features

- Short circuit rated 10us @  $T_C = 100^\circ\text{C}$ ,  $V_{GE} = 15\text{V}$
- High speed switching
- Low saturation voltage :  $V_{CE(\text{sat})} = 2.2\text{ V}$  @  $I_C = 15\text{A}$
- High input impedance
- CO-PAK, IGBT with FRD :  $t_{fr} = 42\text{ns}$  (typ.)

#### Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.



#### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Description	SGH15N60RUF	Units
$V_{CES}$	Collector-Emitter Voltage	600	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C = 25^\circ\text{C}$	24	A
	Collector Current @ $T_C = 100^\circ\text{C}$	15	A
$I_{CM(1)}$	Pulsed Collector Current	45	A
$I_F$	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	15	A
$I_{FM}$	Diode Maximum Forward Current	160	A
$T_{SC}$	Short Circuit Withstand Time @ $T_C = 100^\circ\text{C}$	10	us
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	160	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	64	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

#### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(\text{IGBT})$	Thermal Resistance, Junction-to-Case	--	0.77	$^\circ\text{C}/\text{W}$
$R_{\theta JC}(\text{DIODE})$	Thermal Resistance, Junction-to-Case	--	0.7	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	$^\circ\text{C}/\text{W}$

## Electrical Characteristics of the IGBT

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 250\mu\text{A}$	600	--	--	V
$\Delta BV_{CES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 1\text{mA}$	--	0.6	--	$^\circ\text{C}$
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0\text{V}$	--	--	250	$\mu\text{A}$
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0\text{V}$	--	--	$\pm 100$	nA

## On Characteristics

$V_{GE(\text{th})}$	G-E Threshold Voltage	$I_C = 15\text{mA}, V_{CE} = V_{GE}$	5.0	6.0	8.5	V
$V_{CE(\text{sat})}$	Collector to Emitter Saturation Voltage	$I_C = 15\text{A}, V_{GE} = 15\text{V}$	--	2.2	2.8	V
		$I_C = 24\text{A}, V_{GE} = 15\text{V}$	--	2.5	--	V

## Dynamic Characteristics

$C_{ies}$	Input Capacitance	$V_{CE} = 30\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	--	948	--	pF
$C_{oes}$	Output Capacitance		--	101	--	pF
$C_{res}$	Reverse Transfer Capacitance		--	33	--	pF

## Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 300\text{ V}, I_C = 15\text{A}, R_G = 13\Omega, V_{GE} = 15\text{V}, \text{Inductive Load, } T_C = 25^\circ\text{C}$	--	17	--	ns
$t_r$	Rise Time		--	33	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	44	65	nS
$t_f$	Fall Time		--	118	200	ns
$E_{on}$	Turn-On Switching Loss		--	320	--	uJ
$E_{off}$	Turn-Off Switching Loss		--	356	--	uJ
$E_{ts}$	Total Switching Loss		--	676	950	uJ
$t_{d(on)}$	Turn-On Delay Time		--	20	--	ns
$t_r$	Rise Time		--	34	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	48	70	ns
$t_f$	Fall Time		--	212	350	ns
$E_{on}$	Turn-On Switching Loss		--	340	--	uJ
$E_{off}$	Turn-Off Switching Loss		--	695	--	uJ
$E_{ts}$	Total Switching Loss		--	1035	1450	uJ
$T_{sc}$	Short Circuit Withstand Time	$V_{CC} = 300\text{ V}, V_{GE} = 15\text{V}$ @ $T_C = 100^\circ\text{C}$	10	--	--	us
$Q_g$	Total Gate Charge	$V_{CE} = 300\text{ V}, I_C = 15\text{A}, V_{GE} = 15\text{V}$	--	42	60	nC
$Q_{ge}$	Gate-Emitter Charge		--	7	10	nC
$Q_{gc}$	Gate-Collector Charge		--	17	24	nC
$L_e$	Internal Emitter Inductance	Measured 5mm from PKG	--	14	--	nH

## Electrical Characteristics of DIODE

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
$V_{FM}$	Diode Forward Voltage	$I_F = 15\text{A}$	$T_C = 25^\circ\text{C}$	--	1.4	1.7	V
			$T_C = 100^\circ\text{C}$	--	1.3	--	
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 15\text{A}, di/dt = 200\text{ A/us}$	$T_C = 25^\circ\text{C}$	--	42	60	ns
			$T_C = 100^\circ\text{C}$	--	60	--	
$I_{rr}$	Diode Peak Reverse Recovery Current	$I_F = 15\text{A}, di/dt = 200\text{ A/us}$	$T_C = 25^\circ\text{C}$	--	3.5	6.0	A
			$T_C = 100^\circ\text{C}$	--	5.6	--	
$Q_{rr}$	Diode Reverse Recovery Charge	$T_C = 25^\circ\text{C}$	--	80	180	--	nC
			$T_C = 100^\circ\text{C}$	--	220	--	

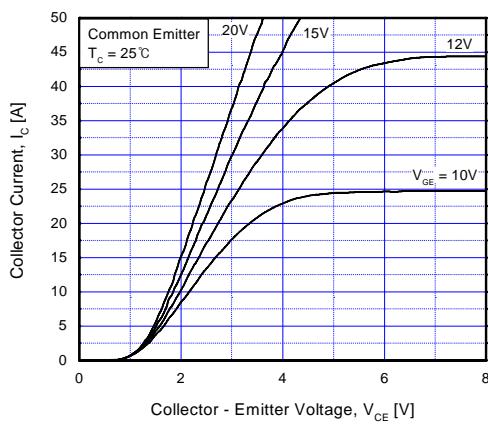


Fig 1. Typical Output Characteristics

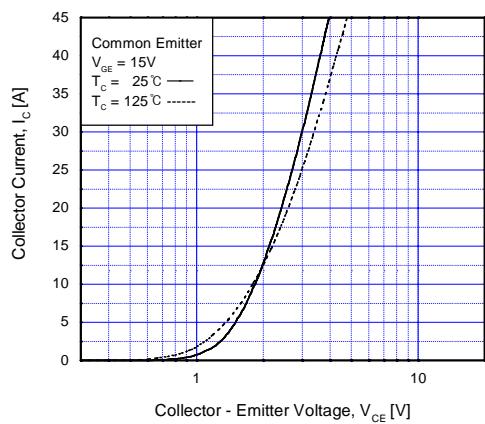


Fig 2. Typical Saturation Voltage Characteristics

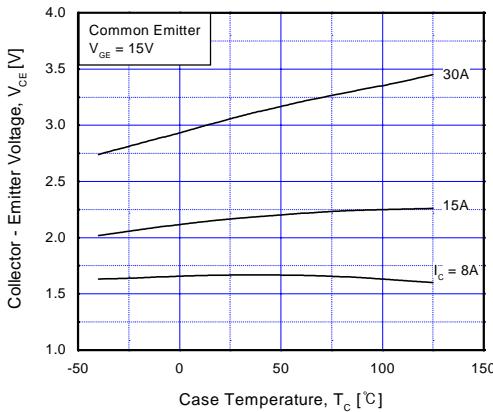


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

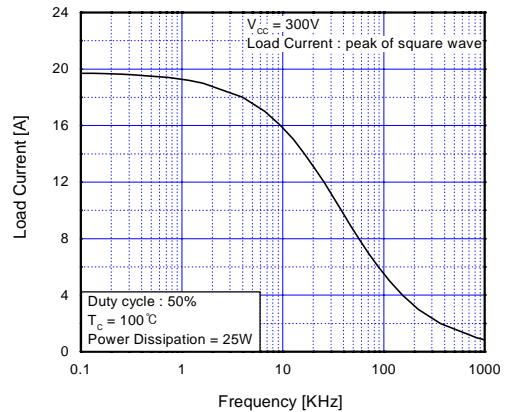
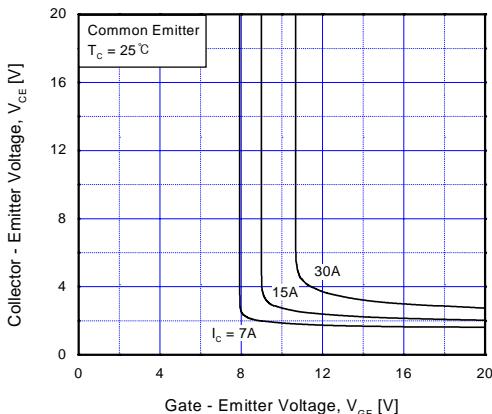
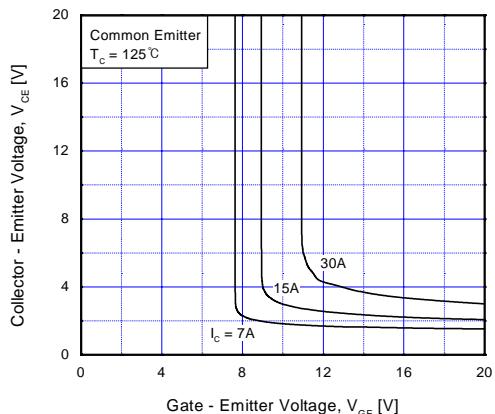


Fig 4. Load Current vs. Frequency

Fig 5. Saturation Voltage vs.  $V_{GE}$ Fig 6. Saturation Voltage vs.  $V_{GE}$

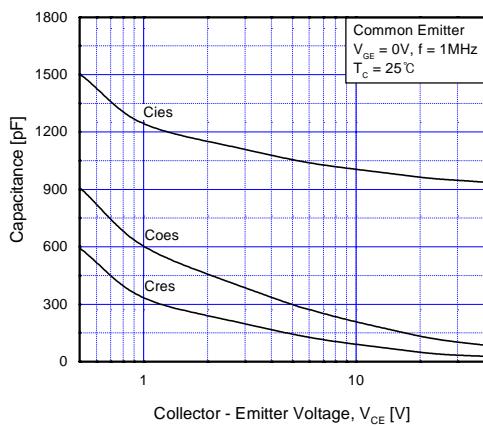


Fig 7. Capacitance Characteristics

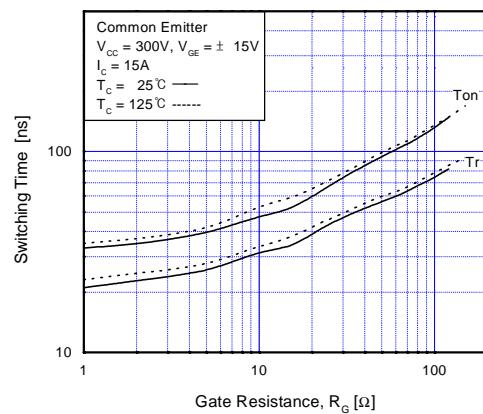


Fig 8. Turn-On Characteristics vs. Gate Resistance

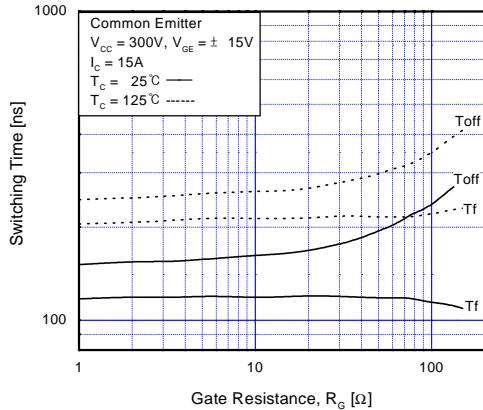


Fig 9. Turn-Off Characteristics vs. Gate Resistance

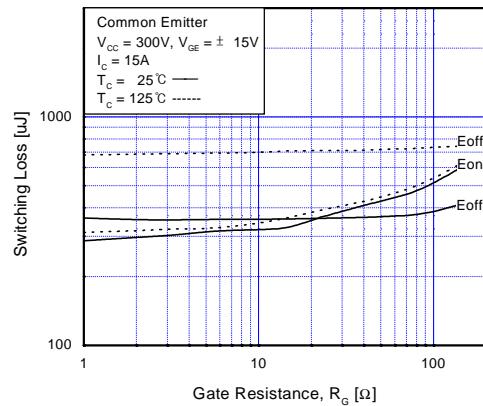


Fig 10. Switching Loss vs. Gate Resistance

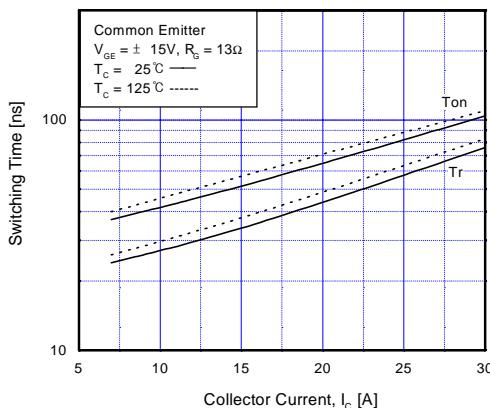


Fig 11. Turn-On Characteristics vs. Collector Current

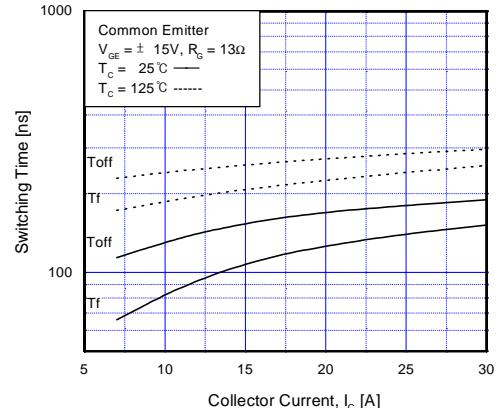


Fig 12. Turn-Off Characteristics vs. Collector Current

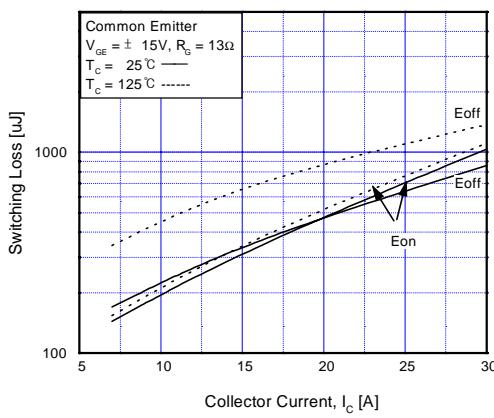


Fig 13. Switching Loss vs. Collector Current

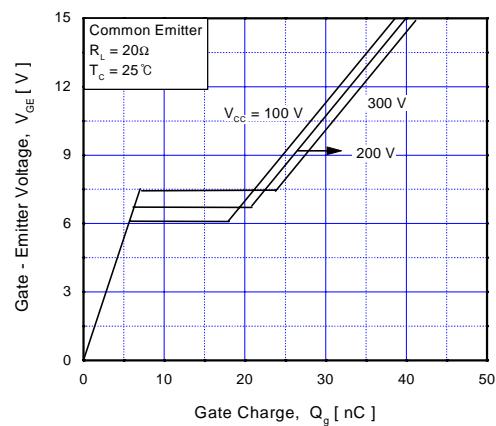


Fig 14. Gate Charge Characteristics

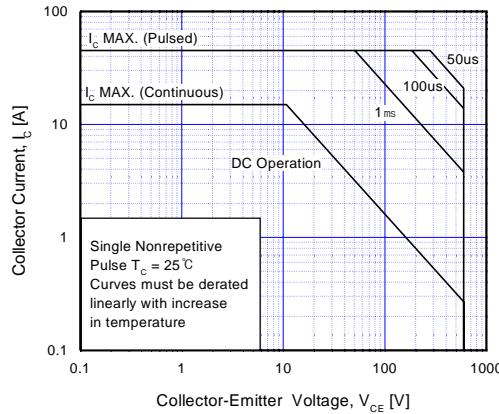


Fig 15. SOA Characteristics

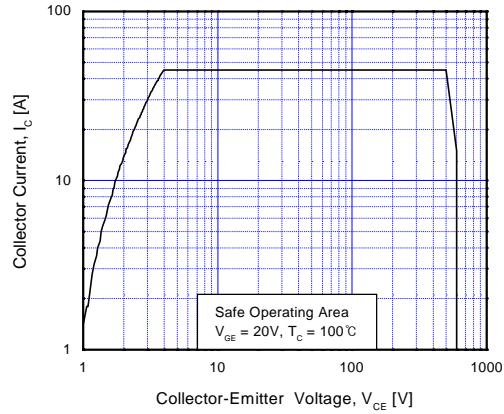


Fig 16. Turn-Off SOA Characteristics

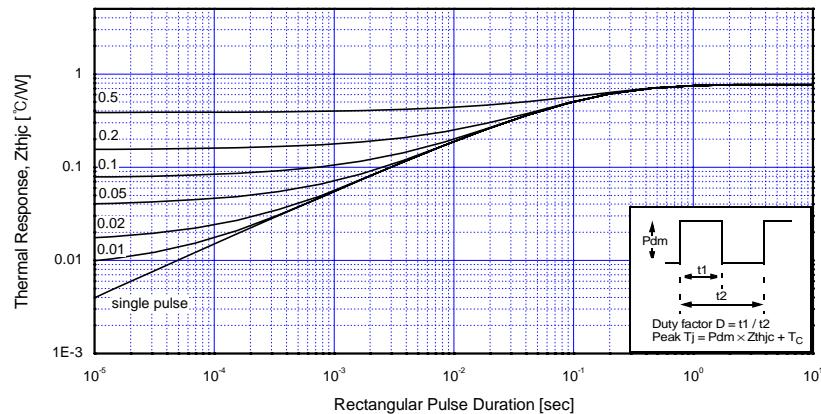
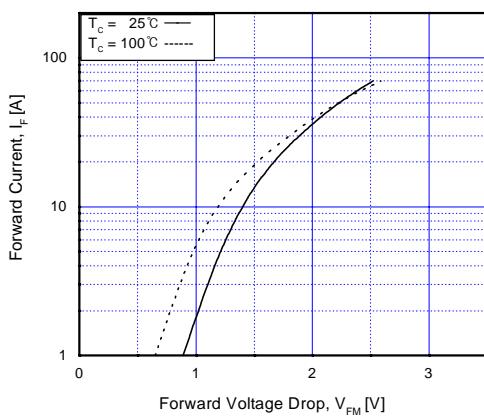
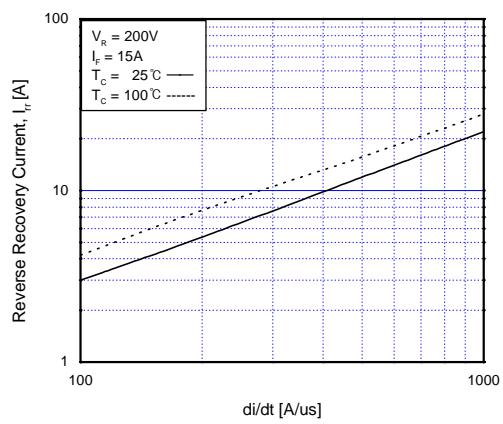
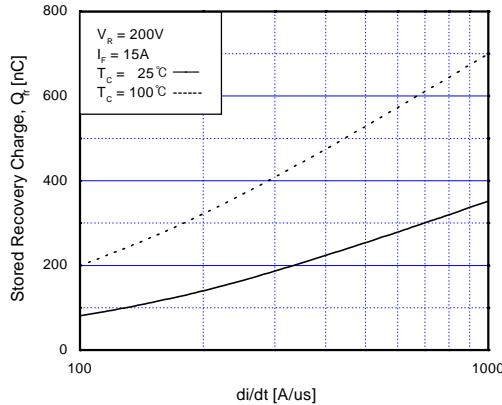
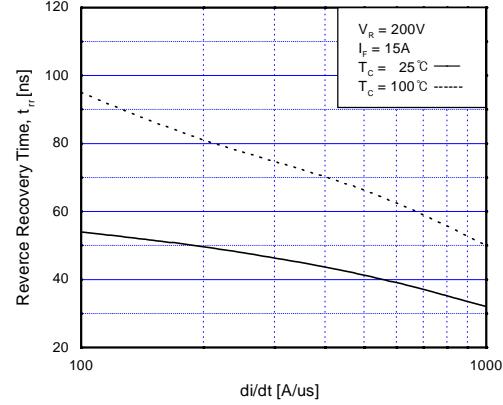


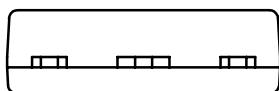
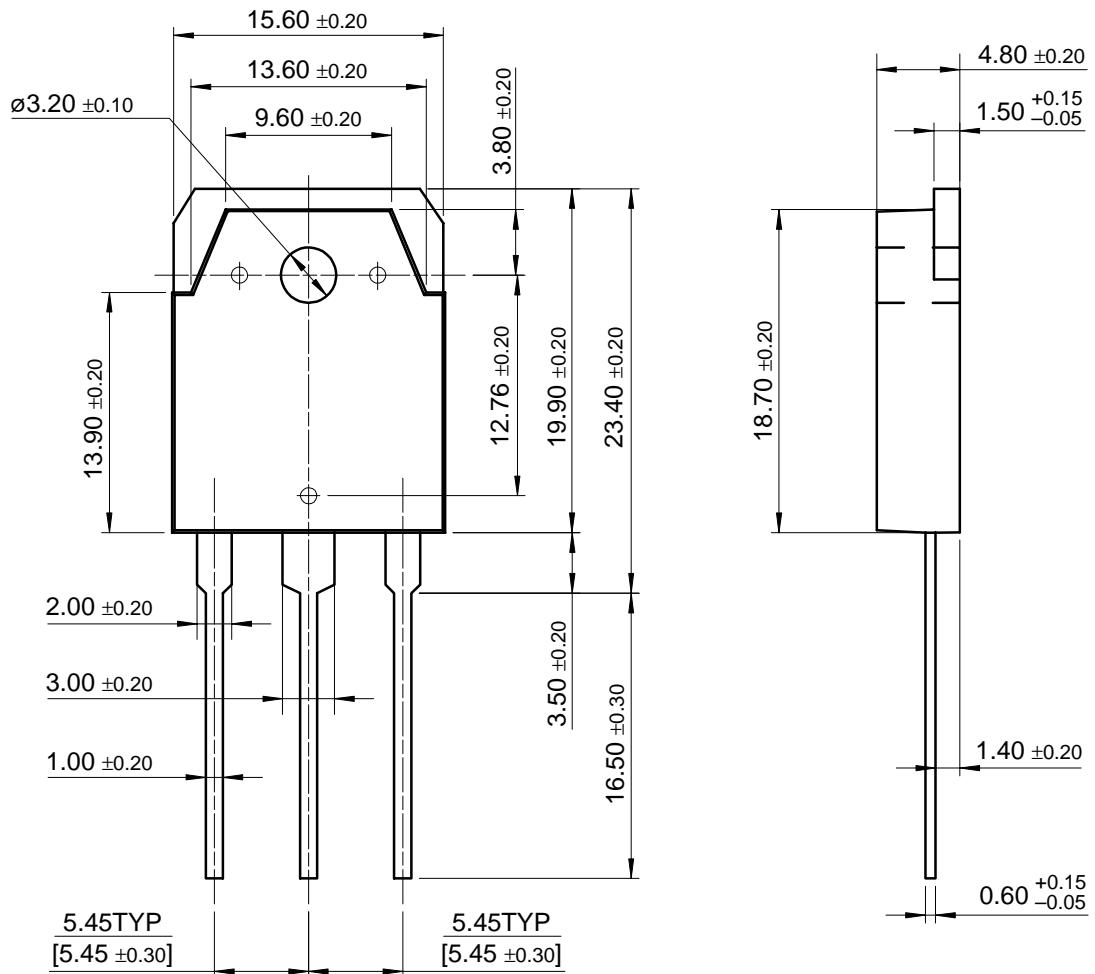
Fig 17. Transient Thermal Impedance of IGBT

**Fig 18. Forward Characteristics****Fig 19. Reverse Recovery Current****Fig 20. Stored Charge****Fig 21. Reverse Recovery Time**

**SGH15N60RUF**

**Package Dimension**

**TO-3P**



Dimensions in Millimeters

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